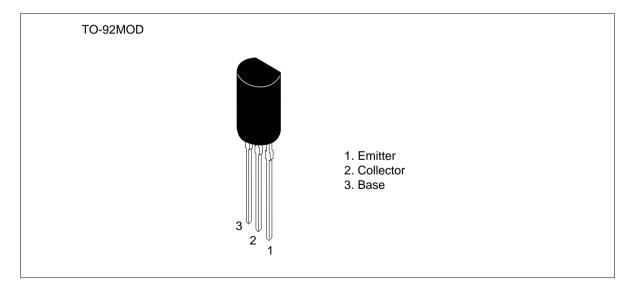
Silicon NPN Epitaxial

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Application

- Low frequency power amplifier
- Complementary pair with 2SB562

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	25	V
Collector to emitter voltage	V _{CEO}	20	V
Emitter to base voltage	V _{EBO}	5	V
Collector current	Ι _c	1.0	А
Collector peak current	i _{C(peak)}	1.5	А
Collector power dissipation	Pc	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

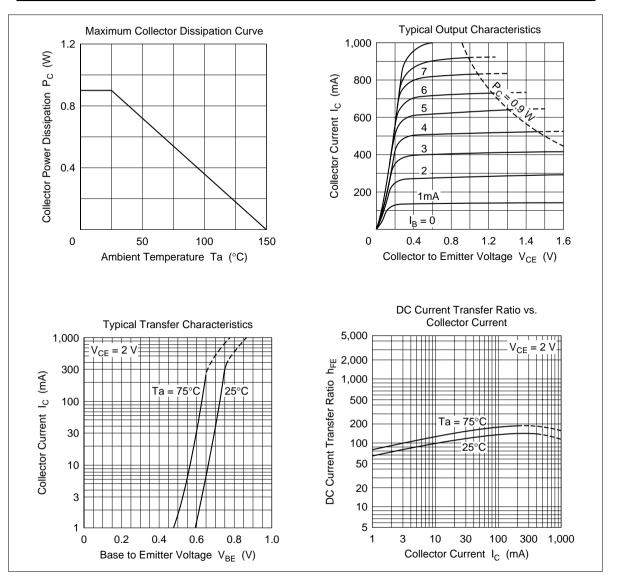
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	25	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	20	—	_	V	$I_c = 1 \text{ mA}, \text{ R}_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	—	1.0	μΑ	$V_{CB} = 20 \text{ V}, \text{ I}_{E} = 0$
DC current transfer ratio	h _{FE} *1	85	—	240		$V_{ce} = 2 \text{ V}, \text{ I}_{c} = 0.5 \text{ A}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	0.2	0.5	V	$I_{\rm C} = 0.8$ A, $I_{\rm B} = 0.08$ A* ²
Base to emitter voltage	V _{BE}	_	0.79	1.0	V	$V_{ce} = 2 \text{ V}, \text{ I}_{c} = 0.5 \text{ A}^{*2}$
Gain bandwidth product	f _T	_	190		MHz	$V_{ce} = 2 \text{ V}, \text{ I}_{c} = 0.5 \text{ A}^{*2}$
Collector output capacitance	Cob		22		pF	$V_{_{CB}} = 10 \text{ V}, \text{ I}_{_{E}} = 0, \text{ f} = 1 \text{ MHz}$

Notes: 1. The 2SD468 is grouped by h_{FE} as follows.

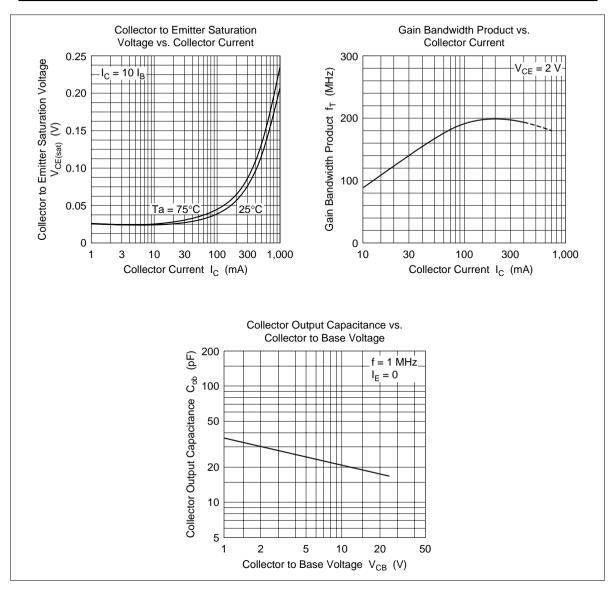
2. Pulse test C

В

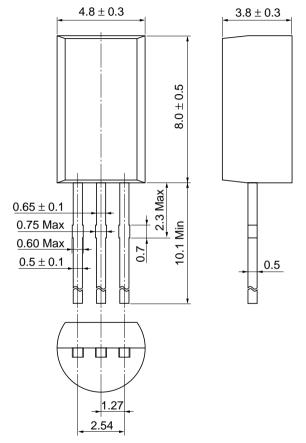
85 to170 120 to 240



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Unit: mm



Hitachi Code	TO-92 Mod
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.35 g

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